MAX14434-MAX14436

Four-Channel, Fast, Low-Power, 5kV_{RMS} Digital Isolators

General Description

The MAX14434–MAX14436 are the fastest, lowest power, 4-channel, digital galvanic isolators on the market today using Maxim's proprietary process technology. These devices transfer digital signals between circuits with different power domains while using as little as 0.58mW per channel at 1Mbps with a 1.8V supply. The MAX14434/5/6 have an isolation rating of 5kV_{RMS} for 60 seconds.

The MAX14434–MAX14436 family offers all three possible unidirectional channel configurations to accommodate any 4-channel design, including SPI, RS-232, RS-485, and digital I/O applications. Output enable for the A side of the MAX14435R/S/U/V is activelow, making them ideal for isolating a port on a shared SPI bus since the CS signal can directly enable the MISO signal on the isolator. All other devices in the family have the traditional active-high enable.

Devices are available with a maximum data rate of either 25Mbps or 200Mbps and with outputs that are either default-high or default-low. The default is the state the output assumes when the input is either not powered or is open-circuit. See the <u>Ordering Information</u> for suffixes associated with each option. Independent 1.71V to 5.5V supplies on each side of the isolator also make the devices suitable for use as level translators.

The MAX14434–MAX14436 are available in a 16-pin wide-body SOIC package with 8mm of creepage and clearance. The package material has a minimum comparative tracking index (CTI) of 600V, which gives it a group 1 rating in creepage tables. All devices are rated for operation at ambient temperatures of -40°C to +125°C.

Benefits and Features

- Robust Galvanic Isolation for Fast Digital Signals
 - · 200Mbps Data Rate
 - Withstands 5kV_{RMS} for 60s (V_{ISO})
 - Continuously Withstands 848V_{RMS} (V_{IOWM})
 - Withstands ±10kV Surge between GNDA and GNDB with 1.2/50µs waveform
 - High CMTI (50kV/µs, Typical)
- Low Power Consumption
 - 1.1mW per Channel at 1Mbps with V_{DD} = 3.3V
 - 3.5mW per Channel at 100Mbps with V_{DD} = 1.8V
- Options to Support a Broad Range of Applications
 - 2 Data Rates (25Mbps, 200Mbps)
 - · 3 Channel Direction Configurations
 - 2 Output Default States (High/Low)

Applications

- Fieldbus Communications for Industrial Automation
- Isolated RS-485/RS-422, CAN
- General Isolation Application
- Battery Management
- Medical Systems

Safety Regulatory Approvals (Pending)

- UL According to UL1577
- cUL According to CSA Bulletin 5A
- VDE 0884-10

Ordering Information appears at end of data sheet.



Absolute Maximum Ratings

0.3V to +6V
0.3V to +6V
0.3V to +6V
0.3V to +6V
0.3V to (V _{DDA} + 0.3V)
0.3V to (V _{DDB} + 0.3V)
Continuous

Continuous Power Dissipation (T _A =	+70°C)
Wide SOIC (derate 14.1mW/°C at	ove +70°C)1126.8mW
Operating Temperature Range	40°C to +125°C
Maximum Junction Temperature	+150°C
Storage Temperature Range	60°C to +150°C
Soldering Temperature (reflow)	+260°C

Package Thermal Characteristics (Note 1)

Wide SOIC

Junction-to-Ambient Thermal Resistance (θ_{JA})......71°C/W Junction-to-Case Thermal Resistance (θ_{JC}).....24°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

DC Electrical Characteristics

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)} \text{ (Note 2)}$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
POWER SUPPLY							
Supply Voltage	V _{DDA}	Relative to GNDA	Relative to GNDA			5.5	V
Supply Voltage	V_{DDB}	Relative to GNDB		1.71		5.5	\ \ \
Undervoltage-Lockout Threshold	V _{UVLO} _	V _{DD} _ rising		1.5	1.6	1.66	V
Undervoltage-Lockout Threshold Hysteresis	V _{UVLO_HYST}				45		mV
			V _{DDA} = 5V		0.52	0.96	
		500kHz square wave, C _L = 0pF	V _{DDA} = 3.3V		0.51	0.93	
			V _{DDA} = 2.5V		0.50	0.92	
			V _{DDA} = 1.8V		0.49	0.64	
			V _{DDA} = 5V		1.63	2.42	
Supply Current (MAX14434_)	ļ	12.5MHz square	V _{DDA} = 3.3V		1.59	2.36	mA
(Note 3)	I _{DDA}	wave, C _L = 0pF	V _{DDA} = 2.5V		1.58	2.33	
			V _{DDA} = 1.8V		1.54	2.00	
			V _{DDA} = 5V		4.5	6.14	
		50MHz square	V _{DDA} = 3.3V		4.39	6.00	
		wave, C _L = 0pF	V _{DDA} = 2.5V		4.35	5.93]
			V _{DDA} = 1.8V		4.21	5.43	

DC Electrical Characteristics (continued)

 $(V_{DDA}-V_{GNDA}=1.71V~to~5.5V,~V_{DDB}-V_{GNDB}=1.71V~to~5.5V,~C_L=15pF,~T_A=-40^{\circ}C~to~+125^{\circ}C,~unless~otherwise~noted.~Typical~values~are~at~V_{DDA}-V_{GNDA}=3.3V,~V_{DDB}-V_{GNDB}=3.3V,~V_{GNDA}=V_{GNDB},~T_A=+25^{\circ}C,~unless~otherwise~noted.)~(Note~2)$

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
			V _{DDB} = 5V		0.87	1.47	
		500kHz square	V _{DDB} = 3.3V		0.82	1.41	
		wave, C _L = 0pF	V _{DDB} = 2.5V		0.81	1.39]
			V _{DDB} = 1.8V		0.79	1.32	
			V _{DDB} = 5V		2.97	3.84	
Supply Current (MAX14434_)		12.5MHz square	V _{DDB} = 3.3V		2.00	2.74	
(Note 3)	I _{DDB}	wave, C _L = 0pF	V _{DDB} = 2.5V		1.69	2.36	- mA
			V _{DDB} = 1.8V		1.43	2.02	
			V _{DDB} = 5V		9.52	11.17	
		50MHz square	V _{DDB} = 3.3V		5.68	6.88	
		wave, C _L = 0pF	V _{DDB} = 2.5V		4.45	5.38]
			V _{DDB} = 1.8V		3.46	4.18	
			V _{DDA} = 5V		0.62	1.10	
		500kHz square	V _{DDA} = 3.3V		0.60	1.06	
		wave, C _L = 0pF	V _{DDA} = 2.5V		0.59	1.05	mA
			V _{DDA} = 1.8V		0.57	0.83	
			V _{DDA} = 5V		1.98	2.80	
	l	12.5MHz square	V _{DDA} = 3.3V		1.70	2.47	
	I _{DDA}	wave, C _L = 0pF	V _{DDA} = 2.5V		1.61	2.35	
			V _{DDA} = 1.8V		1.52	2.02	
		50MHz square wave, C _L = 0pF	V _{DDA} = 5V		5.77	7.43	
			V _{DDA} = 3.3V		4.73	6.25	
			V _{DDA} = 2.5V		4.38	5.81	
Supply Current (MAX14435_)			V _{DDA} = 1.8V		4.03	5.15	
(Note 3)			V _{DDB} = 5V		0.78	1.35	
		500kHz square	V _{DDB} = 3.3V		0.75	1.30	
		wave, C _L = 0pF	V _{DDB} = 2.5V		0.74	1.28	1
			V _{DDB} = 1.8V		0.72	1.16	
			V _{DDB} = 5V		2.64	3.49	
		12.5MHz square	V _{DDB} = 3.3V		1.90	2.65	m A
	I _{DDB}	wave, C _L = 0pF	V _{DDB} = 2.5V		1.66	2.36	- mA
			V _{DDB} = 1.8V		1.46	2.03]
			V _{DDB} = 5V		8.26	9.91]
		50MHz square	V _{DDB} = 3.3V		5.36	6.66	
	1	wave, C _L = 0pF	V _{DDB} = 2.5V		4.42	5.52	
			V _{DDB} = 1.8V		3.66	4.51	

DC Electrical Characteristics (continued)

 $(V_{DDA}-V_{GNDA}=1.71V~to~5.5V,~V_{DDB}-V_{GNDB}=1.71V~to~5.5V,~C_L=15pF,~T_A=-40^{\circ}C~to~+125^{\circ}C,~unless~otherwise~noted.~Typical~values~are~at~V_{DDA}-V_{GNDA}=3.3V,~V_{DDB}-V_{GNDB}=3.3V,~V_{GNDA}=V_{GNDB},~T_A=+25^{\circ}C,~unless~otherwise~noted.)~(Note~2)$

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
			V _{DDA} = 5V		0.70	1.22	
		500kHz square	V _{DDA} = 3.3V		0.67	1.17	
		wave, C _L = 0pF	V _{DDA} = 2.5V		0.66	1.16	
			V _{DDA} = 1.8V		0.64	0.99	
			V _{DDA} = 5V		2.31	3.15	
		12.5MHz square	V _{DDA} = 3.3V		1.81	2.56	mA
	I _{DDA}	wave, C _L = 0pF	V _{DDA} = 2.5V		1.64	2.35	
			V _{DDA} = 1.8V		1.50	2.02	
			V _{DDA} = 5V		7.04	8.70	
		50MHz square wave, C _L = 0pF	V _{DDA} = 3.3V		5.06	6.46	-
			V _{DDA} = 2.5V		4.40	5.67	
Supply Current (MAX14436_)			V _{DDA} = 1.8V		3.85	4.83	
(Note 3)		500kHz square wave, C _L = 0pF	V _{DDB} = 5V		0.70	1.24	
			V _{DDB} = 3.3V		0.67	1.19	
			V _{DDB} = 2.5V		0.66	1.17	
			V _{DDB} = 1.8V		0.65	1.00	
			V _{DDB} = 5V		2.31	3.15	
	l	12.5MHz square	V _{DDB} = 3.3V		1.80	2.57	mA
	I _{DDB}	wave, C _L = 0pF	V _{DDB} = 2.5V		1.64	2.36	l IIIA
			V _{DDB} = 1.8V		1.49	2.03	
			V _{DDB} = 5V		7.01	8.66	
		50MHz square	V _{DDB} = 3.3V		5.04	6.46	
		wave, C _L = 0pF	V _{DDB} = 2.5V		4.40	5.67	
			V _{DDB} = 1.8V		3.84	4.83	

DC Electrical Characteristics (continued)

 $(V_{DDA} - V_{GNDA} = 1.71 \text{V to } 5.5 \text{V}, V_{DDB} - V_{GNDB} = 1.71 \text{V to } 5.5 \text{V}, C_L = 15 \text{pF}, T_A = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } V_{DDA} - V_{GNDA} = 3.3 \text{V}, V_{DDB} - V_{GNDB} = 3.3 \text{V}, V_{GNDA} = V_{GNDB}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.)} \text{ (Note 2)}$

PARAMETER	SYMBOL	CON	IDITIONS	MIN	TYP	MAX	UNITS
LOGIC INPUTS AND OUTPUTS							•
Inc. of Link Voltage	V _{IH}	EN_, IN_, relative to GND_	2.25V ≤ V _{DD} _ ≤ 5.5V	0.7 x V _{DD} _			V
Input High Voltage		EN_, IN_, relative to GND_	1.71V ≤ V _{DD} _ < 2.25V	0.75 x V _{DD} _			V
Input Low Voltage	V.	EN_, IN_, relative to GND_	2.25V ≤ V _{DD} _ ≤ 5.5V			0.8	V
Input Low Voltage	V_{IL}	EN_, IN_, relative to GND_	1.71V ≤ V _{DD} _ < 2.25V			0.7	V
Input Hustoroois	V	EN_, IN_, relative to GND_	MAX1443_ B/E/R/U		410		- mV
Input Hysteresis	V _{HYS}	EN_, IN_, relative to GND_	MAX1443_C/F/S/V		80		IIIV
Input Pullup Current (Note 4)	I _{PU}	IN_, MAX1443_B	S/C/R/S	-10	-5	-1.5	μA
Input Pulldown Current (Note 4)	I _{PD}	IN_, MAX1443_E	/F/U/V	1.5	5	10	μA
EN Pullup Current (Note 4)	I _{PU_EN}	EN_		-10	-5	-1.5	μA
Input Capacitance	C _{IN}	IN_, f _{SW} = 1MHz			2		pF
Output Voltage High (Note 4)	V _{OH}	V _{OUT} _ relative to GND_ I _{OUT} _ = 4mA source		V _{DD} _ - 0.4			V
Output Voltage Low (Note 4)	V _{OL}	V _{OUT} _ relative to I _{OUT} _ = 4mA sink	GND_			0.4	V

Dynamic Characteristics MAX1443_C/F/S/V

 $(V_{DDA}-V_{GNDA}=1.71V~to~5.5V,~V_{DDB}-V_{GNDB}=1.71V~to~5.5V,~C_{L}=15pF,~T_{A}=-40^{\circ}C~to~+125^{\circ}C,~unless~otherwise~noted.~Typical~values~are~at~V_{DDA}-V_{GNDA}=3.3V,~V_{DDB}-V_{GNDB}=3.3V,~V_{GNDA}=V_{GNDB},~T_{A}=+25^{\circ}C,~unless~otherwise~noted.)~(Note~3)$

PARAMETER	SYMBOL	(CONDITIONS	MIN	TYP	MAX	UNITS
Common-Mode Transient Immunity	СМТІ	IN_ = GND_	IN_ = GND_ or V _{DD_} (Note 5)		50		kV/μs
Maximum Data Rate	DD	2.25V ≤ V _{DD}	_ ≤ 5.5V	200			Mhaa
Maximum Data Rate	DR _{MAX}	1.71V ≤ V _{DD}	_ ≤ 1.89V	150			Mbps
Minimum Pulse Width	PW _{MIN}	IN_ to	2.25V ≤ V _{DD} _ ≤ 5.5V			5	ns
William Calob Widan	1 VVMIIN	OUT_	1.71V ≤ V _{DD} _ ≤ 1.89V			6.67	
			4.5V ≤ V _{DD} _ ≤ 5.5V	4.1	5.4	9.2	
	t _{PLH} OUT	IN_ to	3.0V ≤ V _{DD} _ ≤ 3.6V	4.2	5.9	10.2	
		C _L = 15pF	2.25V ≤ V _{DD} _ ≤ 2.75V	4.9	7.1	13.4	
Propagation Delay (Figure 1)			1.71V ≤ V _{DD} _ ≤ 1.89V	7.1	10.9	20.3	ns
(riguio 1)		IN_ to OUT_,	4.5V ≤ V _{DD} _ ≤ 5.5V	4.3	5.6	9.4	
	t _{PHL}		$3.0V \le V_{DD} \le 3.6V$	4.4	6.2	10.5	-
	PHL	C _L = 15pF	$2.25V \le V_{DD} \le 2.75V$	5.1	7.3	14.1	
			1.71V ≤ V _{DD} _ ≤ 1.89V	7.2	10.9	21.7	
Pulse Width Distortion	PWD	tplh -tphl			0.3	2	ns
		4.5V ≤ V _{DD} _	≤ 5.5V			3.7	
	4	3.0V ≤ V _{DD} _	≤ 3.6V			4.3	
	^t SPLH	2.25V ≤ V _{DD}	2.25V ≤ V _{DD} _ ≤ 2.75V			6	
Propagation Delay Skew		1.71V ≤ V _{DD}	_ ≤ 1.89V			10.3	ns
Part-to-Part (Same Channel)		4.5V ≤ V _{DD} _	≤ 5.5V			3.8	
		3.0V ≤ V _{DD} _	≤ 3.6V			4.7	
	tsphl	2.25V ≤ V _{DD} _ ≤ 2.75V				6.5	
		1.71V ≤ V _{DD}	_ ≤ 1.89V			11.5	
Propagation Delay Skew	ew t _{SCSLH}		_ ≤ 5.5V			1.5	
Channel-to-Channel (Same Direction)	t _{SCSHL}	1.71V ≤ V _{DD}	_ ≤ 5.5V			1.5	ns

Dynamic Characteristics MAX1443_C/F/S/V (continued)

 $(V_{DDA}-V_{GNDA}=1.71V~to~5.5V,~V_{DDB}-V_{GNDB}=1.71V~to~5.5V,~C_{L}=15pF,~T_{A}=-40^{\circ}C~to~+125^{\circ}C,~unless~otherwise~noted.~Typical~values~are~at~V_{DDA}-V_{GNDA}=3.3V,~V_{DDB}-V_{GNDB}=3.3V,~V_{GNDA}=V_{GNDB},~T_{A}=+25^{\circ}C,~unless~otherwise~noted.)~(Note~3)$

PARAMETER	SYMBOL	(CONDITIONS	MIN	TYP	MAX	UNITS
		4.5V ≤ V _{DD} _	≤ 5.5V			2.9	
		3.0V ≤ V _{DD} _			3.4		
	tscolh	2.25V ≤ V _{DD}	_ ≤ 2.75V			4.9	
Propagation Delay Skew Channel-to-Channel		1.71V ≤ V _{DD}	_ ≤ 1.89V			10.2	
(Opposite Direction)		4.5V ≤ V _{DD} _	≤ 5.5V			3.2	ns
	t	3.0V ≤ V _{DD} _	≤ 3.6V			3.8	
	t _{SCOHL}	2.25V ≤ V _{DD}	_ ≤ 2.75V			5.3	
		1.71V ≤ V _{DD}	_ ≤ 1.89V			10.9	
Peak Eye Diagram Jitter	T _{JIT(PK)}	200Mbps			90		ps
Clock Jitter RMS	T _{JCLK(RMS)}	500kHz Clock	Input, Rising/Falling Edges		6.5		ps
Rise Time		4.5V ≤ V _{DD} _ ≤ 5.5V				1.6	
	t_	3.0V ≤ V _{DD} _ ≤ 3.6V				2.2	ns
Nise Time	t _R	2.25V ≤ V _{DD} _ ≤ 2.75V				3	113
		1.71V ≤ V _{DD} _ ≤ 1.89V				4.5	
		$4.5 \text{V} \le \text{V}_{\text{DD}} \le 5.5 \text{V}$				1.4	
Fall Time	t-	$3.0 \text{V} \le \text{V}_{\text{DD}} \le 3.6 \text{V}$				2	ns
I dii TiiTic	t _F	$2.25 \text{V} \le \text{V}_{\text{DD}} \le 2.75 \text{V}$				2.8	115
		1.71V ≤ V _{DD}	_ ≤ 1.89V			5.1	
		ENA to	4.5V ≤ V _{DD} _ ≤ 5.5V			3.5	
Enable to Data Valid	+	OUT_, ENB to	$3.0V \le V_{DD} \le 3.6V$			5.8	ns
Litable to Data Valid	t _{EN}	OUT_,	2.25V ≤ V _{DD} _ ≤ 2.75V			9.3	115
		C _L = 15pF	1.71V ≤ V _{DD} _ ≤ 1.89V			17.4	
		ENA to	4.5V ≤ V _{DD} _ ≤ 5.5V			6.4	ns
Enable to Tristate	t	OUT_, ENB to	3.0V ≤ V _{DD} _ ≤ 3.6V			9.2	
LITADIC IO TITOLALE	t _{TRI}	OUT_,	2.25V ≤ V _{DD} _ ≤ 2.75V			12.8	
		C _L = 15pF	1.71V ≤ V _{DD} _ ≤ 1.89V			19.4	

Dynamic Characteristics MAX1443_B/E/R/U

 $(V_{DDA}-V_{GNDA}=1.71V~to~5.5V,~V_{DDB}-V_{GNDB}=1.71V~to~5.5V,~C_{L}=15pF,~T_{A}=-40^{\circ}C~to~+125^{\circ}C,~unless~otherwise~noted.~Typical~values~are~at~V_{DDA}-V_{GNDA}=3.3V,~V_{DDB}-V_{GNDB}=3.3V,~V_{GNDA}=V_{GNDB},~T_{A}=+25^{\circ}C,~unless~otherwise~noted.)~(Note~3)$

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
Common-Mode Transient Immunity	CMTI	IN_ = GND_	or V _{DD} (Note 5)		50		kV/µs
Maximum Data Rate	DR _{MAX}			25			Mbps
Minimum Pulse Width	PW _{MIN}	IN_ to OUT_				40	ns
Glitch Rejection		IN_ to OUT_		10	17	29	ns
			4.5V ≤ V _{DD} _ ≤ 5.5V	17.4	23.9	32.5	
	t _{PLH} O	IN_ to OUT_,	$3.0V \le V_{DD} \le 3.6V$	17.6	24.4	33.7	
		C _L = 15pF	$2.25V \le V_{DD} \le 2.75V$	18.3	25.8	36.7	
Propagation Delay		'	1.71V ≤ V _{DD} _ ≤ 1.89V	20.7	29.6	43.5	ns
(Figure 1)			4.5V ≤ V _{DD} _ ≤ 5.5V	16.9	23.4	33.6] 115
	t	IN_ to OUT_,	$3.0V \le V_{DD} \le 3.6V$	17.2	24.2	35.1	
	t _{PHL}	C _L = 15pF	$2.25V \le V_{DD} \le 2.75V$	17.8	25.4	38.2	
			1.71V ≤ V _{DD} _ ≤ 1.89V	19.8	29.3	45.8	
Pulse Width Distortion	PWD	t _{PLH} -t _{PHL}			0.4	4	ns
		4.5V ≤ V _{DD} _	4.5V ≤ V _{DD} _ ≤ 5.5V			15.1	
	t _{SPLH}	3.0V ≤ V _{DD} _	≤ 3.6V			15	
	SPLH	2.25V ≤ V _{DD}	_ ≤ 2.75V			15.4	
Propagation Delay Skew		1.71V ≤ V _{DD}	_ ≤ 1.89V			20.5	ns
Part-to-Part (Same Channel)		4.5V ≤ V _{DD} _	≤ 5.5V			13.9	113
	topuu	$3.0V \le V_{DD} \le 3.6V$				14.2	
	tsphl	2.25V ≤ V _{DD}	_ ≤ 2.75V			16	
		1.71V ≤ V _{DD}	_ ≤ 1.89V			21.8	
Propagation Delay Skew Channel-to-Channel	tscslh	1.71V ≤ V _{DD}	_ ≤ 5.5V			2	ns
(Same Direction)	tscshl	1.71V ≤ V _{DD}	_ ≤ 5.5V			2	115
		4.5V ≤ V _{DD} _	≤ 5.5V			13.9	
		3.0V ≤ V _{DD} _	≤ 3.6V			13.7	
	tscolh	2.25V ≤ V _{DD}				14.2	
Propagation Delay Skew		1.71V ≤ V _{DD} _ ≤ 1.89V				19.4	
Channel-to-Channel (Opposite Direction)		4.5V ≤ V _{DD} _	≤ 5.5V			13	ns
,		3.0V ≤ V _{DD}	≤ 3.6V			12.9	1
	tscohi	2.25V ≤ V _{DD}				14.4	
		1.71V ≤ V _{DD}	≤ 1.89V			20.1]

Dynamic Characteristics MAX1443_B/E/R/U (continued)

 $(V_{DDA} - V_{GNDA} = 1.71V \text{ to } 5.5V, V_{DDB} - V_{GNDB} = 1.71V \text{ to } 5.5V, C_L = 15pF, T_A = -40^{\circ}\text{C} \text{ to } +125^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $V_{DDA} - V_{GNDA} = 3.3V, V_{DDB} - V_{GNDB} = 3.3V, V_{GNDA} = V_{GNDB}, T_A = +25^{\circ}\text{C}, \text{ unless otherwise noted.}$ (Note 3)

PARAMETER	SYMBOL	(CONDITIONS	MIN	TYP	MAX	UNITS		
Peak Eye Diagram Jitter	T _{JIT(PK)}	25Mbps			250		ps		
		4.5V ≤ V _{DD} _	≤ 5.5V			1.6			
Dies Time (Figure 1)		3.0V ≤ V _{DD} _	≤ 3.6V			2.2			
Rise Time (Figure 1)	t _R	2.25V ≤ V _{DD}	_ ≤ 2.75V			3	ns		
		1.71V ≤ V _{DD}	_ ≤ 1.89V			4.5			
Fall Time (Figure 1)		4.5V ≤ V _{DD} _	≤ 5.5V			1.4			
	t _F	3.0V ≤ V _{DD} _ ≤ 3.6V				2			
		2.25V ≤ V _{DD} _ ≤ 2.75V				2.8	ns		
			1.71V ≤ V _{DD}	$1.71V \le V_{DD_{-}} \le 1.89V$		1.71V ≤ V _{DD} _ ≤ 1.89V			5.1
				ENA to	4.5V ≤ V _{DD} _ ≤ 5.5V			3.5	
Enable to Data Valid	+	OUT_, ENB to	$3.0V \le V_{DD} \le 3.6V$			5.8	5.8		
Enable to Data Valid	t _{EN}	OUT_,	$2.25V \le V_{DD} \le 2.75V$			9.3	ns		
		C _L = 15pF	1.71V ≤ V _{DD} _ ≤ 1.89V			17.4			
		ENA to	4.5V ≤ V _{DD} _ ≤ 5.5V			6.4			
Fachla to Triatata	4	OUT_,	$3.0V \le V_{DD} \le 3.6V$			9.2			
Enable to Tristate	t _{TRI}	ENB to OUT_, C _L = 15pF	2.25V ≤ V _{DD} _ ≤ 2.75V			12.8	ns		
			1.71V ≤ V _{DD} _ ≤ 1.89V			19.4			

- Note 2: All devices are 100% production tested at $T_A = +25$ °C. Specifications over temperature are guaranteed by design.
- Note 3: Not production tested. Guaranteed by design and characterization,
- **Note 4:** All currents into the device are positive. All currents out of the device are negative. All voltages are referenced to their respective ground (GNDA or GNDB), unless otherwise noted.
- Note 5: CMTI is the maximum sustainable common-mode voltage slew rate while maintaining the correct output. CMTI applies to both rising and falling common-mode voltage edges. Tested with the transient generator connected between GNDA and GNDB (V_{CM} = 1000V).

ESD Protection

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ESD		Human Body Model, All Pins		±4		kV

Table 1. Insulation Characteristics

PARAMETER	SYMBOL	CONDITIONS	VALUE	UNITS
Partial Discharge Test Voltage	V _{PR}	Method B1 = V _{IORM} x 1.875 (t = 1s, partial discharge < 5pC)	2250	V _P
Maximum Repetitive Peak Isolation Voltage	V _{IORM}	(Note 6)	1200	V _P
Maximum Working Isolation Voltage	V _{IOWM}	Continuous RMS voltage (Note 6)	848	V _{RMS}
Maximum Transient Isolation Voltage	V _{IOTM}	t = 1s	8400	V _P
Maximum Withstand Isolation Voltage	V _{ISO}	f _{SW} = 60Hz, duration = 60s (Note 7)	5000	V _{RMS}
Maximum Surge Isolation Voltage	V _{IOSM}	Basic Insulation, 1.2/50µs pulse per IEC61000-4-5	10	kV
Insulation Resistance	R _S	V _{IO} = 500V	>1012	Ω
Barrier Capacitance Side A to Side B	CIO	f _{SW} = 1MHz (Note 8)	2	pF
Minimum Creepage Distance	CPG		8	mm
Minimum Clearance Distance	CLR		8	mm
Internal Clearance		Distance through insulation	0.015	mm
Comparative Tracking Index	СТІ	Material Group I (IEC 60112)	>600	
Climate Category			40/125/21	
Pollution Degree (DIN VDE 0110, Table 1)			2	

Note 6: V_{ISO} , V_{IOWM} , and V_{IORM} are defined by the IEC 60747-5-5 standard. Note 7: Product is qualified at V_{ISO} for 60s and 100% production tested at 120% of V_{ISO} for 1s. Note 8: Capacitance is measured with all pins on field-side and logic-side tied together.

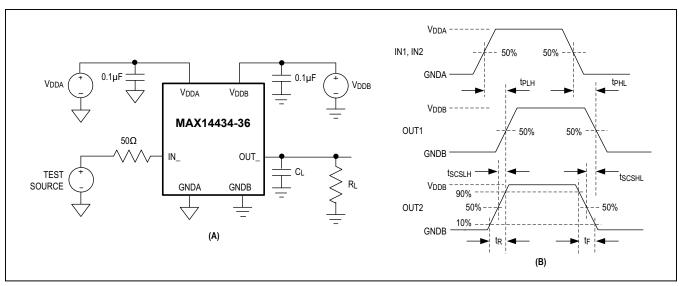
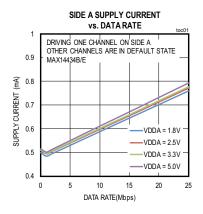


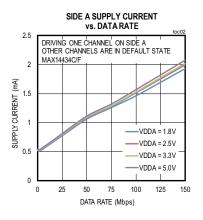
Figure 1. Test Circuit (A) and Timing Diagram (B)

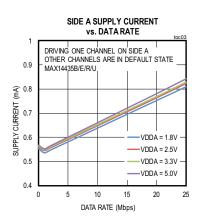
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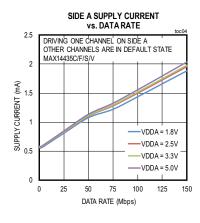
Typical Operating Characteristics

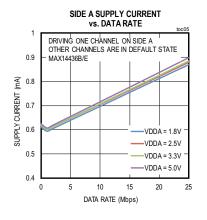
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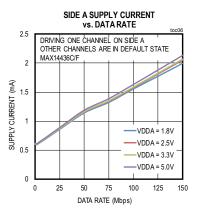


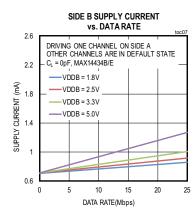


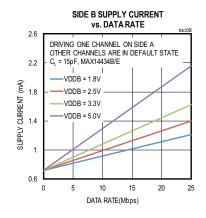


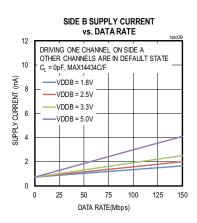






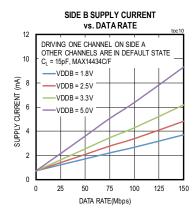


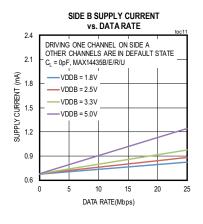


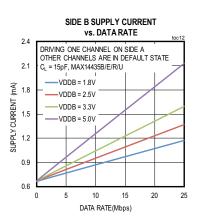


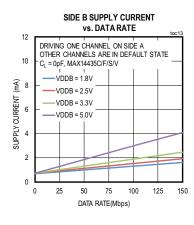
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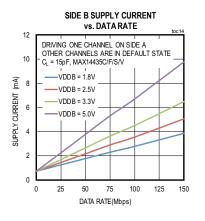
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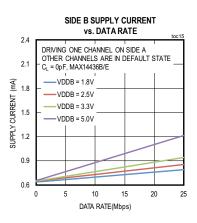


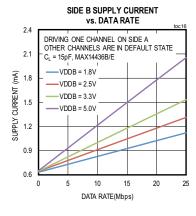


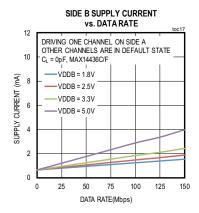


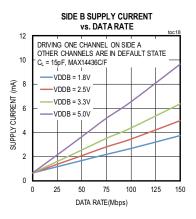






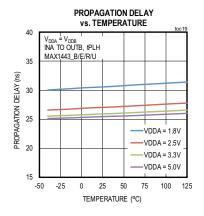


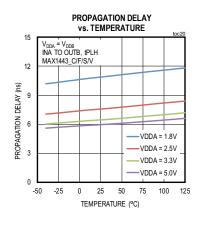


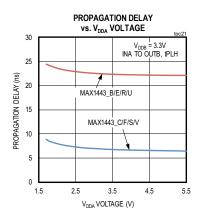


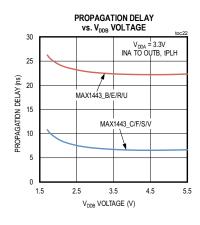
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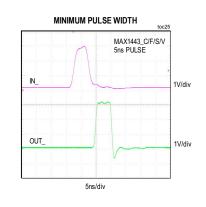
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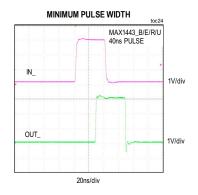


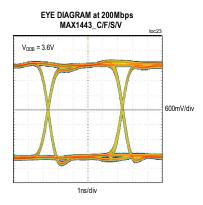


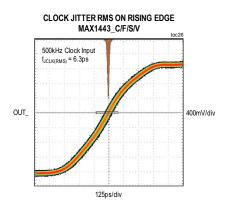


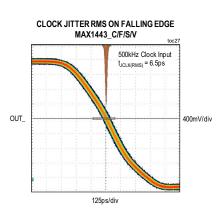




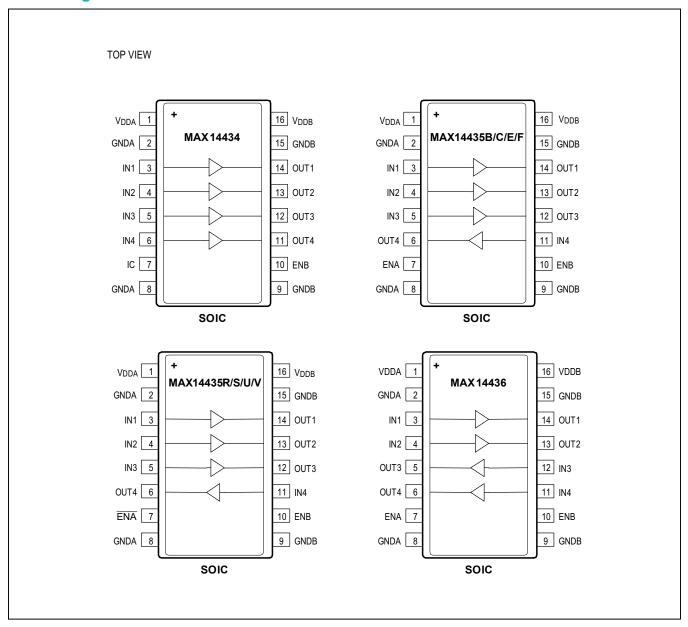








Pin Configurations

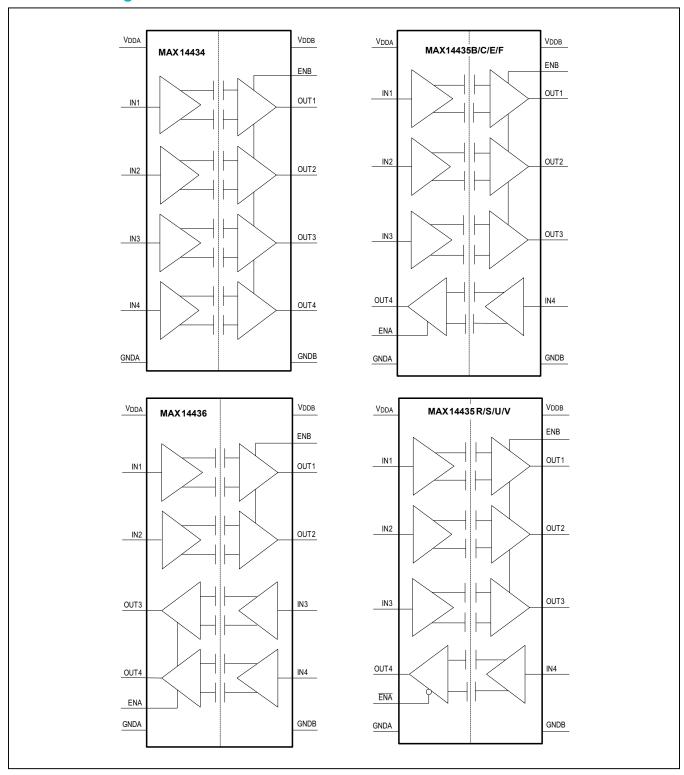


Four-Channel, Fast, Low-Power, 5kV_{RMS} Digital Isolators

Pin Description

		PI	N				
NAME	MAX14434 MAX14435B/C/E/F		MAX14435R/S/U/V	MAX14436	FUNCTION		
V_{DDA}	1	1	1	1	Power Supply. Bypass V _{DDA} with a 0.1µF ceramic capacitor as close as possible to the pin.		
GNDA	2, 8	2, 8	2, 8	2, 8	Ground Reference for Side A		
IN1	3	3	3	3	Logic Input 1 on Side A, corresponds to Logic Output 1 on Side B		
IN2	4	4	4	4	Logic Input 2 on Side A, corresponds to Logic Output 2 on Side B		
IN3	5	5	5	12	Logic Input 3 on Side A or B, corresponds to Logic Output 3 on Side B or A		
IN4	6	11	11	11	Logic Input 4 on Side A or B, corresponds to Logic Output 4 on Side B or A		
I.C.	7	_	_	_	Internally Connected. Leave unconnected or connect to GNDA or V _{DDA} .		
ENA	_	7	_	7	Active-High Enable for Side A. ENA has an internal 5μA pullup to V _{DDA} .		
ENA	_	_	7	_	Active-Low Enable for Side A. ENA has an internal 5μA pullup to V _{DDA}		
OUT1	14	14	14	14	Logic Output 1 on Side B		
OUT2	13	13	13	13	Logic Output 2 on Side B		
OUT3	12	12	12	5	Logic Output 3 on Side A or Side B		
OUT4	11	6	6	6 Logic Output 4 on Side A or Side B			
ENB	10	10	10	10	Active-High Enable for Side B. ENB has an internal 5µA pullup to V _{DDB} .		
GNDB	9, 15	9, 15	9, 15	9, 15	Ground Reference for Side B		
V _{DDB}	16	16	16	16	Power Supply. Bypass V _{DDB} with a 0.1µF ceramic capacitor as close as possible to the pin.		

Functional Diagram



Four-Channel, Fast, Low-Power, 5kV_{RMS} Digital Isolators

Detailed Description

The MAX14434–MAX14436 is a family of 4-channel digital isolators. The MAX14434–MAX14436 have an isolation rating of 5kV_{RMS}. The MAX14434–MAX14436 family offers all three possible unidirectional channel configurations to accommodate any 4-channel design, including SPI, RS-232, RS-485, and digital I/O applications. For applications requiring bidirectional channels, such as I²C, see the MAX14933 and MAX14937.

The MAX14434 features four channels transferring digital signals in one direction for applications such as isolated digital I/O. The MAX14435 has three channels transmitting data in one direction and one channel transmitting in the opposite direction, making it ideal for applications such as isolated SPI and RS-485 communication. The MAX14436 provides further design flexibility with two channels in each direction for isolated RS-232 or other applications.

Devices are available in the 16-pin wide-body SOIC package and are rated for up to 5kV_{RMS}. This family of digital isolators offers low-power operation, high electromagnetic interference (EMI) immunity, and stable temperature performance through Maxim's proprietary process technology. The devices isolate different ground domains and block high-voltage/high-current transients from sensitive or human interface circuitry.

Devices are available with a maximum data rate of either 25Mbps (B/E/R/U versions) or 200Mbps (C/F/S/V versions). Each device can be ordered with default-high or default-low outputs. The default is the state the output assumes when the input is not powered or if the input is open circuit. The devices have two supply inputs (V_{DDA} and V_{DDB}) that independently set the logic levels on either side of the device. V_{DDA} and V_{DDB} are referenced to GNDA and GNDB, respectively. The MAX14434–MAX14436 family also features a refresh circuit to ensure output accuracy when an input remains in the same state indefinitely.

Digital Isolation

The MAX14434–MAX14436 family provides galvanic isolation for digital signals that are transmitted between two ground domains. The devices withstand differences of up to $5kV_{RMS}$ for up to 60 seconds, and up to $1200V_{PEAK}$ of continuous isolation.

Level-Shifting

The wide supply voltage range of both V_{DDA} and V_{DDB} allows the MAX14434–MAX14436 family to be used for level translation in addition to isolation. V_{DDA} and V_{DDB} can be independently set to any voltage from 1.71V to 5.5V. The supply voltage sets the logic level on the corresponding side of the isolator.

Unidirectional Channels

Each channel of the MAX14434–MAX14436 is unidirectional; it only passes data in one direction, as indicated in the functional diagram. Each device features four unidirectional channels that operate independently with guaranteed data rates from DC up to 25Mbps (B/E/R/U versions), or from DC to 200Mbps (C/F/S/V versions). The output driver of each channel is push-pull, eliminating the need for pullup resistors. The outputs are able to drive both TTL and CMOS logic inputs.

Startup and Undervoltage-Lockout

The V_{DDA} and V_{DDB} supplies are both internally monitored for undervoltage conditions. Undervoltage events can occur during power-up, power-down, or during normal operation due to a sagging supply voltage. When an undervoltage condition is detected on either supply while the outputs are enabled, all outputs go to their default states regardless of the state of the inputs (Table 2). Figure 2 through Figure 5 show the behavior of the outputs during power-up and power-down.

V _{IN} _	V _{DDA}	V _{DDB}	ENA	ENB	V _{OUTA}	V _{OUTB}
1	Powered	Powered	1	1	1	1
'			0	0	Hi-Z	Hi-Z
2	Powered	Powered	1	1	0	0
0			0	0	Hi-Z	Hi-Z
	Undervoltage	Powered	1	1	Default	Default
X			0	0	Hi-Z	Hi-Z
Х	Powered	Undervoltage	1	1	Default	Default
			0	0	Hi-Z	Hi-Z

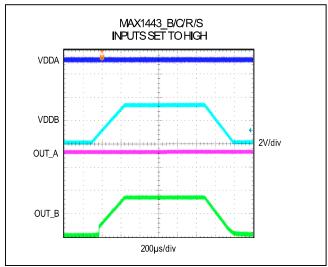


Figure 2. Undervoltage Lockout Behavior (MAX1443_B/C/R/S High)

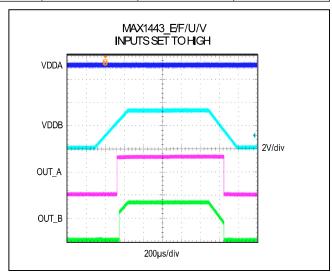


Figure 3. Undervoltage Lockout Behavior (MAX1443_E/F/U/V High)

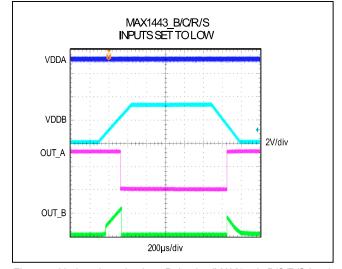


Figure 4. Undervoltage Lockout Behavior (MAX1443_B/C/R/S Low)

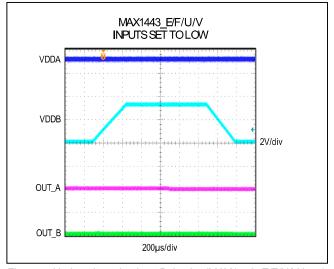


Figure 5. Undervoltage Lockout Behavior (MAX1443_E/F/U/V Low)

Applications Information

Power-Supply Sequencing

The MAX14434–MAX14436 do not require special power supply sequencing. The logic levels are set independently on either side by V_{DDA} and V_{DDB} . Each supply can be present over the entire specified range regardless of the level or presence of the other supply.

Power-Supply Decoupling

To reduce ripple and the chance of introducing data errors, bypass V_{DDA} and V_{DDB} with 0.1µF low-ESR ceramic capacitors to GNDA and GNDB, respectively. Place the bypass capacitors as close to the power supply input pins as possible.

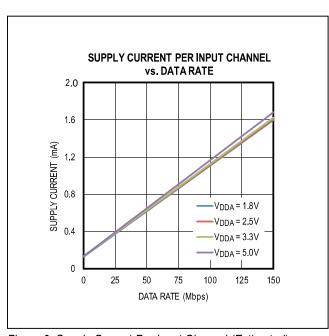


Figure 6. Supply Current Per Input Channel (Estimated)

Layout Considerations

The PCB designer should follow some critical recommendations in order to get the best performance from the design.

- Keep the input/output traces as short as possible.
 Avoid using vias to make low-inductance paths for the signals.
- Have a solid ground plane underneath the highspeed signal layer.
- Keep the area underneath the MAX14434—MAX14436 free from ground and signal planes. Any galvanic or metallic connection between the field-side and logicside defeats the isolation.

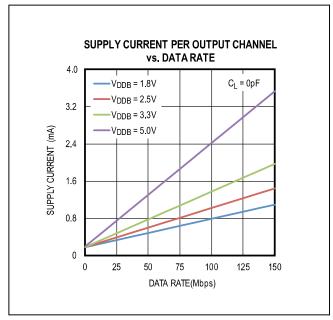


Figure 7. Supply Current Per Output Channel (Estimated)

Calculating Power Dissipation

The required current for a given supply (V_{DDA} or V_{DDB}) can be estimated by summing the current required for each channel. The supply current for a channel depends on whether the channel is an input or an output, the channel's data rate, and the capacitive or resistive load if it is an output. The typical current for an input or output at any data rate can be estimated from the graphs in Figure 6 and Figure 7 are extrapolated from the supply current measurements in a typical operating condition.

The total current for a single channel is the sum of the "no load" current (shown in <u>Figure 6</u> and <u>Figure 7</u>) which is a function of Voltage and Data Rate, and the "load current," which depends on the type of load. Current into a capacitive load is a function of the load capacitance, the switching frequency, and the supply voltage.

$$I_{CL} = C_L \times f_{SW} \times V_{DD}$$

where

 I_{CL} is the current required to drive the capacitive load. C_L is the load capacitance on the isolator's output pin. f_{SW} is the switching frequency (bits per second / 2).

V_{DD} is the supply voltage on the output side of the isolator. Current into a resistive load depends on the load resistance, the supply voltage and the average duty cycle of the data waveform. The DC load current can be conservatively estimated by assuming the output is always high.

$$I_{RL} = V_{DD} \div R_{L}$$

where

 I_{RL} is the current required to drive the resistive load. V_{DD} is the supply voltage on the output side of the isolator. R_{I} is the load resistance on the isolator's output pin.

Example (shown in Figure 8): A MAX14435F is operating with V_{DDA} = 2.5V, V_{DDB} = 3.3V, channel 1 operating at 20Mbps with a 10pF capacitive load, channel 2 held high with a 10kΩ resistive load, and channel 4 operating at 100Mbps with a 15pF capacitive load. Channel 3 is not in use and the resistive load is negligible since the isolator is driving a CMOS input. Refer to Table 3 and Table 4 for V_{DDA} and V_{DDB} supply current calculation worksheets.

V_{DDA} must supply:

- Channel 1 is an input channel operating at 2.5V and 20Mbps, consuming 0.33mA, estimated from Figure 6.
- Channel 2 and 3 are input channels operating at 2.5V with DC signal, consuming 0.13mA, estimated from Figure 6.
- Channel 4 is an output channel operating at 2.5V and 100Mbps, consuming 1.02mA, estimated from Figure 7.
- I_{CL} on channel 4 for 15pF capacitor at 2.5V and 100Mbps is 1.875mA.

Total current for side A = $0.33 + 0.13 \times 2 + 1.02 + 1.875 = 3.485$ mA, typical

VDDB must supply:

- Channel 1 is an output channel operating at 3.3V and 20Mbps, consuming 0.42mA, estimated from Figure 7.
- Channel 2 and 3 are output channels operating at 3.3V with DC signal, consuming 0.18mA, estimated from Figure 7.
- Channel 4 is an input channel operating at 3.3V and 100Mbps, consuming 1.13mA, estimated from Figure 6.
- I_{CL} on channel 1 for 10pF capacitor at 3.3V and 20Mbps is 0.33mA.
- I_{RL} on channel 2 for 10kΩ resistor held at 3.3V is 0.33mA.

Total current for side B = $0.42 + 0.18 \times 2 + 1.13 + 0.33 + 0.33 = 2.57$ mA, typical

Table 3. Side A Supply Current Calculation Worksheet

SIDE A		V _{DDA} = 2.5V							
Channel	IN/ OUT	Data Rate (Mbps)	Load Type	Load	"No Load" Current (mA)	Load Current (mA)			
1	IN	20			0.33				
2	IN	0			0.13				
3	IN	0			0.13				
4	OUT	100	Capacitive	15pF	1.02	2.5V x 50MHz x 15pF = 1.875mA			
	Total: 3.485mA								

Table 4. Side B Supply Current Calculation Worksheet

SIDE B		V _{DDB} = 3.3V							
Channel	IN/ OUT	Data Rate (Mbps)	Load Type	Load	"No Load" Current (mA)	Load Current (mA)			
1	OUT	20	Capacitive	10pF	0.42	3.3V x 10MHz x 10pF = 0.33mA			
2	OUT	0	Resistive	10kΩ	0.18	3.3V / 10kΩ = 0.33mA			
3	OUT	0			0.18				
4	IN	100			1.13				
Total: 2.57mA									

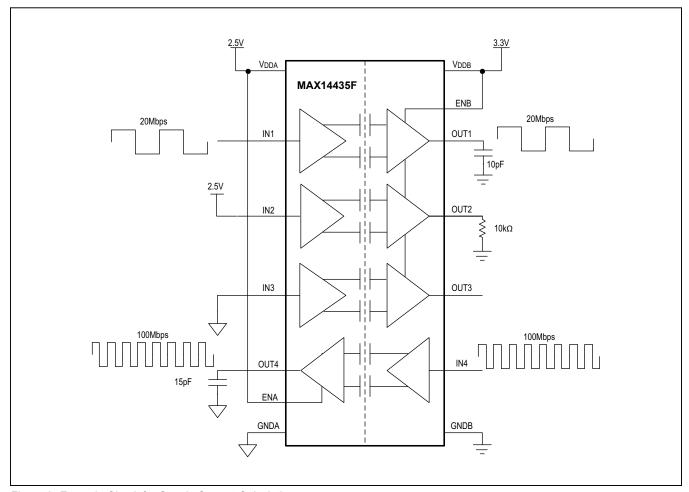
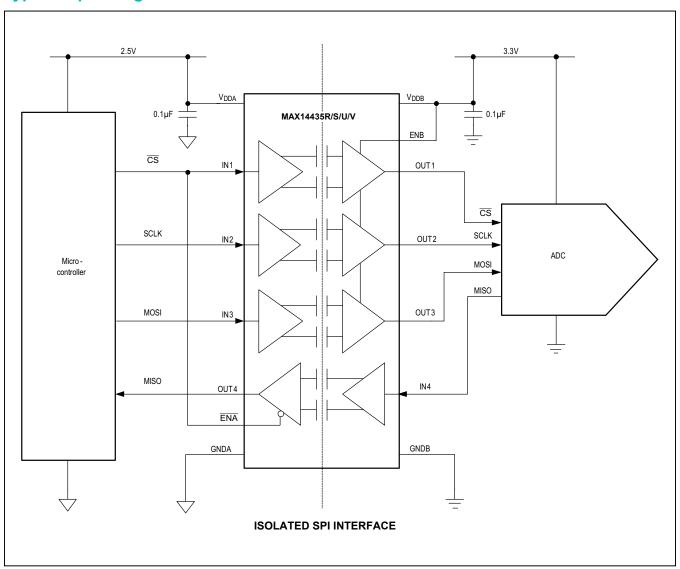
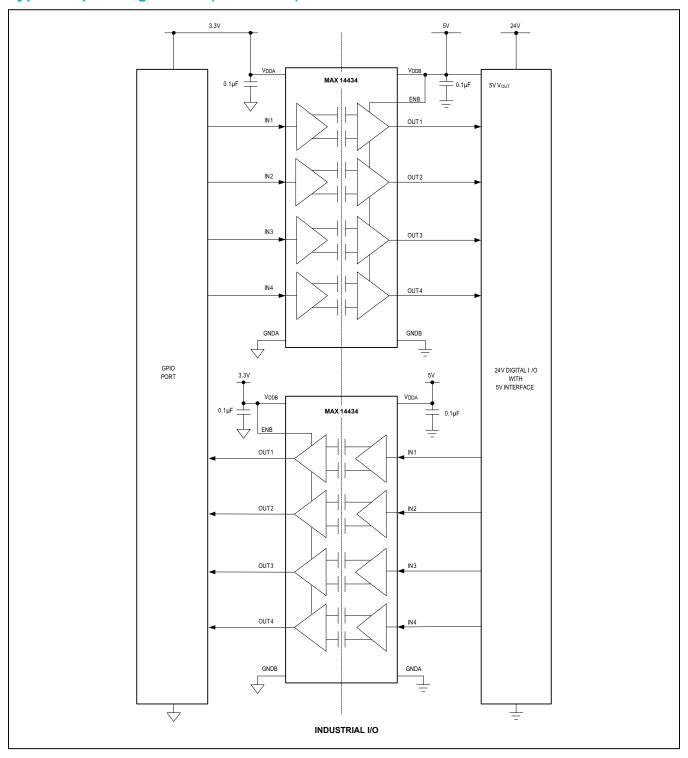


Figure 8. Example Circuit for Supply Current Calculation

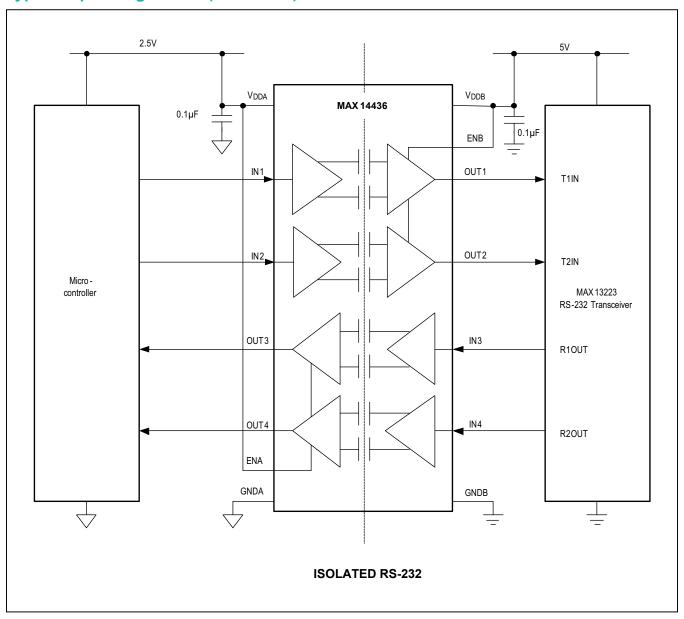
Typical Operating Circuit



Typical Operating Circuit (continued)



Typical Operating Circuit (continued)



Ordering Information

PART	CHANNEL CONFIGU- RATION	DATA RATE (Mbps)	DEFAULT OUTPUT	ENA Polarity	ISOLATION VOLTAGE (kV _{RMS})	TEMP RANGE (°C)	PIN-PACKAGE
MAX14434 BAWE+*	4/0	25	Default High	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14434CAWE+*	4/0	200	Default High	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14434EAWE+*	4/0	25	Default Low	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14434FAWE+*	4/0	200	Default Low	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14435BAWE+*	3/1	25	Default High	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14435CAWE+*	3/1	200	Default High	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14435EAWE+*	3/1	25	Default Low	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14435FAWE+	3/1	200	Default Low	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14435RAWE+*	3/1	25	Default High	Active-Low	5.0	-40 to +125	16 Wide SOIC
MAX14435SAWE+*	3/1	200	Default High	Active-Low	5.0	-40 to +125	16 Wide SOIC
MAX14435UAWE+*	3/1	25	Default Low	Active-Low	5.0	-40 to +125	16 Wide SOIC
MAX14435VAWE+*	3/1	200	Default Low	Active-Low	5.0	-40 to +125	16 Wide SOIC
MAX14436BAWE+*	2/2	25	Default High	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14436CAWE+*	2/2	200	Default High	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14436EAWE+*	2/2	25	Default Low	Active-High	5.0	-40 to +125	16 Wide SOIC
MAX14436FAWE+	2/2	200	Default Low	Active-High	5.0	-40 to +125	16 Wide SOIC

^{*}Future Product—Contact Maxim for availability.

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

MAX14434-MAX14436

Four-Channel, Fast, Low-Power, 5kV_{RMS} Digital Isolators

Package Information

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
16 Wide SOIC	W16MS+12	<u>21-0042</u>	<u>90-0107</u>

Chip Information

PROCESS: BiCMOS

MAX14434-MAX14436

Four-Channel, Fast, Low-Power, 5kV_{RMS} Digital Isolators

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	6/17	Initial release	_
1	8/17	Updated Insulation Characteristics table	10
2	1/18	Updated Ordering Information table	25

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

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